

IN THE SPECIFICATION:

Please replace paragraph number [0007] with the following:

[0007] United States Patent 5,818,107 issued to Pierson et al. teaches an integrated circuit package that utilizes metallization features, located at opposite edges of each chip, to attach a stack of chips to a substrate. The chips are bonded together through their metallization features to form a chip stack, which is then bonded to the substrate. The thickness of the metallization features, in addition to the bonding material used, provides a “stand off” or separation between chips. This separation adds to the overall thickness of the integrated circuit package, making it incompatible for use in electronic devices that require small semiconductor packages.